



TIF™700P Series thermally conductive interface materials are applied to fill the air gaps between the heating elements and the heat dissipation fins or the metal base. Their flexibility and elasticity make them suited to coat very uneven surfaces. Heat can transmit to the metal housing or dissipation plate from the heating elements or even the entire PCB, which effectively enhances the efficiency and life-time of the heat-generating electronic components.

Features

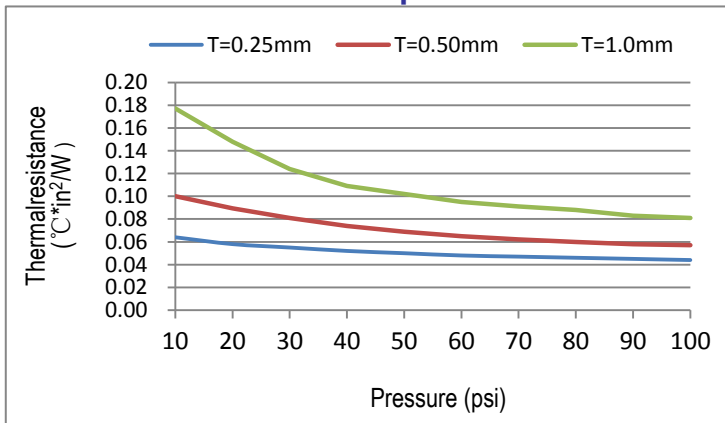
- » Good thermal conductivity
- » Naturally tacky needing no further adhesive coating
- » Soft and Compressible for low stress applications
- » Available in varies thickness

Application

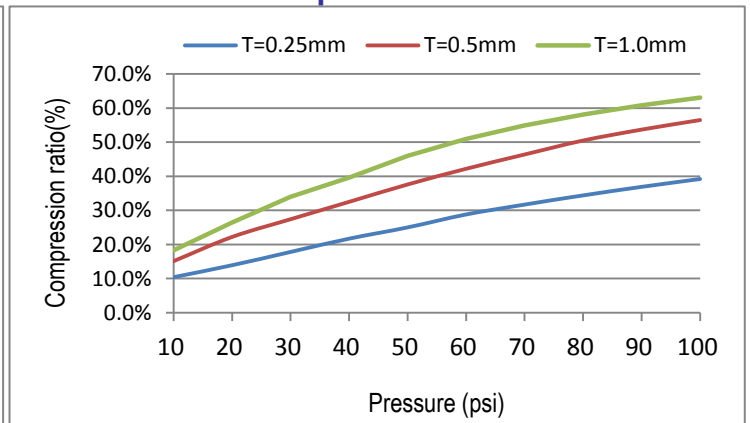
- » Cooling components to the chassis of frame
- » Set Top Box
- » Car Battery & Power Supply
- » Charging Pile
- » LED TV/ Lighting
- » Graphics Card Thermal Module

Typical Properties of TIF™700P Series		
Property	Value	Test method
Color	Gray	Visual
Construction	Ceramic filled silicone elastomer	*****
Thickness range	0.010"(0.25mm)~0.200" (5.0mm)	ASTM D374
Hardness (Shore 00) Thickness>0.75mm	45	ASTM 2240
Hardness (Shore 00) Thickness≤0.75mm	75	ASTM 2240
Specific Gravity (g/cc)	3.3	ASTM D792
Operating Temp	-40~160℃	IEC60068-2-14
Dielectric Breakdown Voltage (T=1.0mm, Vac)	≥5500	ASTM D149
Dielectric Constant@1MHz	4.5	ASTM D150
Volume Resistivity	≥1.0X10 ¹² Ohm-cm	ASTM D257
Thermal Conductivity (W/mK)	7.5	ASTM D5470
	7.5	ISO22007-2.2
Flame Rating	94 -V0	UL E331100

Pressure. vs. Thermal Impedance



Pressure. vs. Compression Ratio



Product Thicknesses: 0.010-inch to 0.200-inch (0.25mm to 5.0mm) **Product Sizes:** 8" x 16"(203mm x406mm)

Individual die cut shapes and custom thickness can be supplied. Please contact us for confirming
 Safe disposal method does not require special protection. The storage condition is low temperature and dry, away from open fire and away from direct sunlight. For detailed method, please refer to the product material safety data sheet.

